



CNC Video Measuring System NEXIV VMZ-K series

CNC Video Measuring System

NEXIV

VMZ-K Series

Confocal Model



NEXIV VMZ-K Series

3D FOV Measurements Generated with Confocal Images

A ground-breaking multifunctional video measuring system developed on the strength of Nikon's leading optomechatronics technology.

- Combines confocal optics and brightfield optics, for fast and accurate evaluation of fine three-dimensional geometries

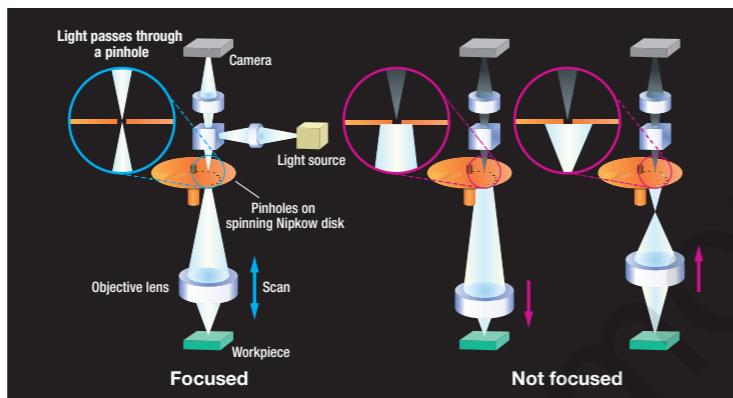
- Allows both 2D and height measurements in the same field of view

This series can be optimally used for inspecting precise 3D-shaped samples, including micro bumps, circuit patterns, and bonding wires, as well as samples with countless points, such as probe cards.

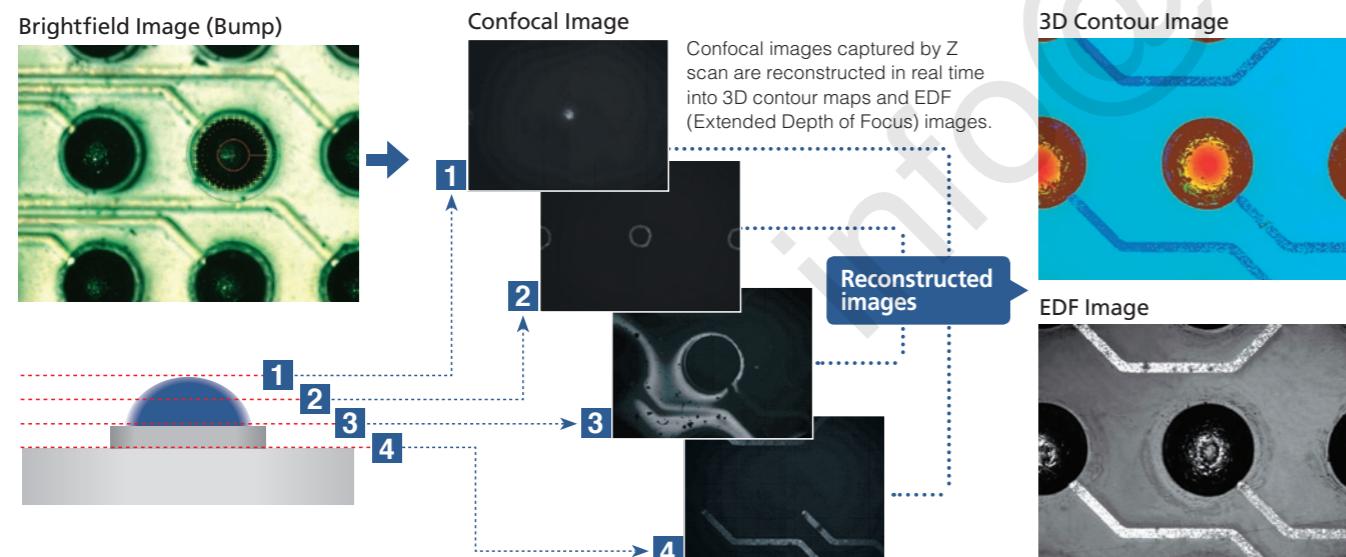
The VMZ-K series can also measure both the shallow recesses and gentle ledges on PCBs.

Principle of Confocal Optics

Light passing through a pinhole on a spinning Nipkow disk is reflected by the workpiece at the focal point, back through the pinhole. This light is detected as a very narrow DOF confocal image by the camera. If there is no workpiece at the focal point, the light does not reflect back through the pinhole. By moving the focal plane in the vertical direction, the Confocal NEXIV VMZ-K series samples multiple confocal images and combines them to compose a confocal image with height information, provided by Nikon's unique interpolation technology.



Nikon-Original Low Flare Confocal Optics



The VMZ-K series enables microscopic height measurements using various objective lenses, with two models to choose from, each featuring different stage strokes.

VMZ-K3040 Type-S/Type-H

Main Features

General model for a wide range of needs

Main Applications

- Microscopic bumps in advanced IC packages
- Probe cards
- Precision optical components
- Microscopic laser marks on semiconductor wafers
- MEMS
- Wire bonding



VMZ-K6555 Type-S/Type-H

Main Features

Handles printed circuit board sizes with its 650 x 550 mm stroke

Main Applications

- PCB with precise circuit patterns
- Probe cards
- LCD-related components



Objectives

Nikon offers five different objective types, enabling users to choose the optimal magnification model for the application.

Magnification	Type-S					Type-H				
	1.5x	3x	7.5x	15x	30x	1.5x	3x	5mm	20mm	5mm
Working Distance	35 mm *1	24 mm	5 mm	20 mm	5 mm	8 x 6 mm	4 x 3 mm	1.6 x 1.2 mm	0.8 x 0.6 mm	0.4 x 0.3 mm
	8 x 6 mm	4 x 3 mm	1.6 x 1.2 mm	0.8 x 0.6 mm	0.4 x 0.3 mm	8 x 6 to 0.53 x 0.4 mm	4 x 3 to 0.27 x 0.2 mm	1.6 x 1.2 to 0.11 x 0.08 mm	1.26 x 0.95 to 0.1 x 0.074 mm	0.63 x 0.47 to 0.05 x 0.04 mm
Field of View	8 x 6 mm	4 x 3 mm	1.6 x 1.2 mm	0.8 x 0.6 mm	0.4 x 0.3 mm	8 x 6 to 0.53 x 0.4 mm	4 x 3 to 0.27 x 0.2 mm	1.6 x 1.2 to 0.11 x 0.08 mm	1.26 x 0.95 to 0.1 x 0.074 mm	0.63 x 0.47 to 0.05 x 0.04 mm
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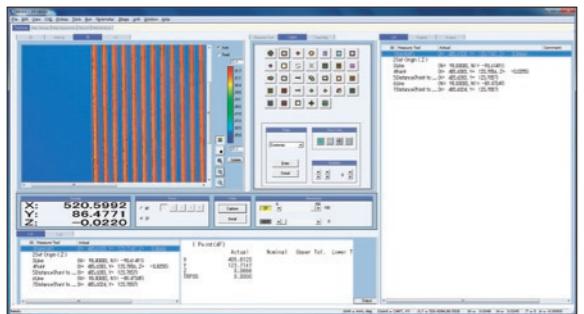
*1: Ring illumination only has a traveling distance of 24 mm.

Field of View	W (mm) x L (mm)	8	4	2.0	1.6	1.26	1.00	0.8	0.63	0.53	0.4	0.27	0.20	0.15	0.11	0.100	0.05	Working distance
Type S	1.5 x	●	●	●	●	●	●	●	●	●	●						24 mm	
	3 x	●	●	●	●	●	●	●	●	●	●						24 mm	
Type H	7.5 x			●	●	●	●	●	●	●	●						5 mm	
	15 x			●	●	●	●	●	●	●	●						20 mm	
	30 x				●	●	●	●	●	●	●						5 mm	

● Brightfield ● Confocal/Brightfield

High performing GUI and sophisticated software functionality provides the easiest and quickest 3D metrology

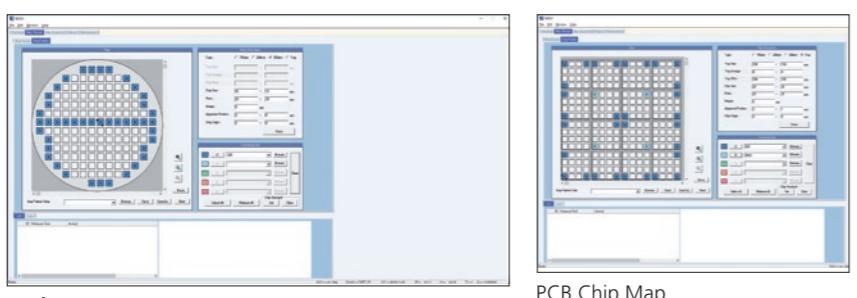
Teaching Generation/Replay



- Both 2D measurement of brightfield images and height measurement of 3D images are possible in the same field of view, at high speeds and with high accuracy.
- In addition to the measurement tools employed by the NEXIV series, 3D feature measurement tools are available for diverse workpiece shapes, such as ball/flat bumps, bonding wires, and probe card pins. The optimized algorithms for measurement sequence enable simultaneous measurement of multiple points in the field of view.
- Measurement results are stored as CSV format ASCII data for Data Reporting/SPC Analysis.

User-friendly operations enhance efficiency of semiconductor wafer and PCB chip measurements.

Map Recipe Generation



Wafer

- Any chip on the generated map can simply be measured by inputting chip size and pitch.
- Map generation can also be done on PCBs, composed of groups of chips.

Map Measurement Execution

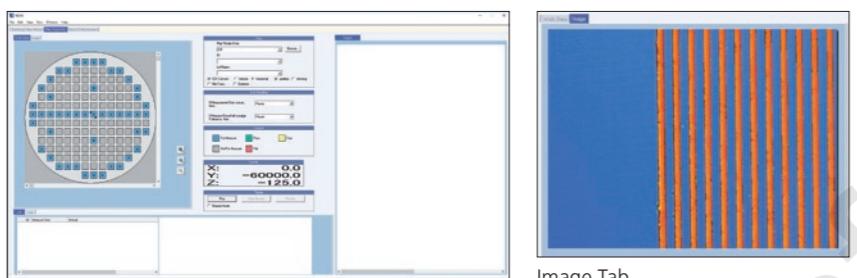
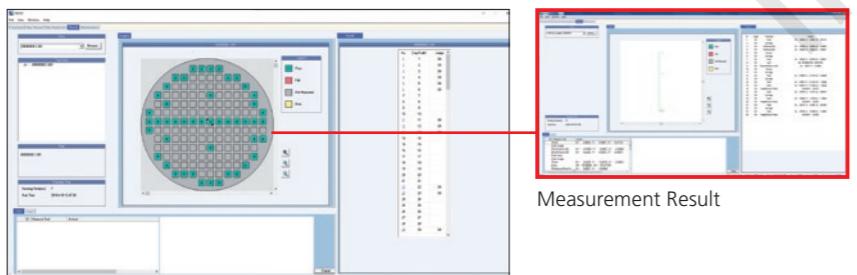


Image Tab

- A specified die can be easily measured by inputting map recipe file, ID, and lot number.
- The workpiece being measured can be viewed by changing to the image tab.

Measurement Result Review



Measurement Result

- The accept/reject status of every die can be graphically reviewed on the map.
- A result screen is shown when a die is selected, making it easy to verify each die's measurement results.

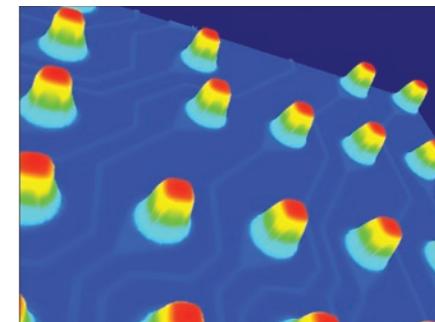
Probe Cards

Programming can be made from location data in one click. XYZ coordinates and coplanarity contact probe pins on probe cards be automatically measured with unique image processing tools.



3D Image

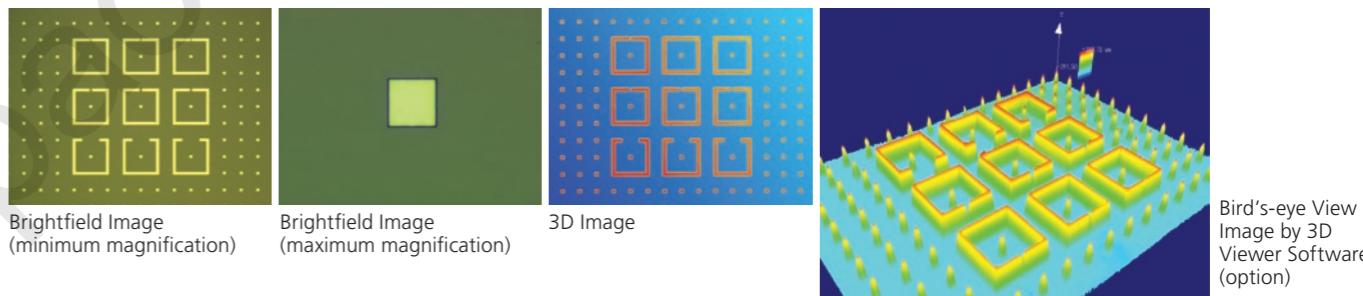
Wafer Level Packages



Bird's-eye View Image with 3D Viewer Software (option)

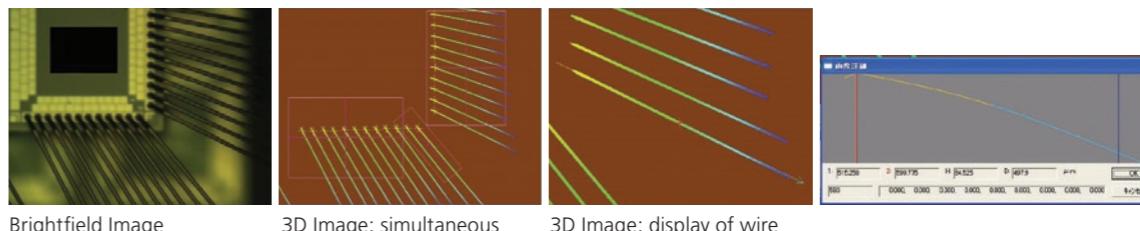
Fine Bump and Substrate Pattern

A combination of 2D measurement with 15x zoom brightfield image and 3D height measurement in the same field of view enables diverse measurements.



Bird's-eye View Image by 3D Viewer Software (option)

Bonding Wire Loop Height

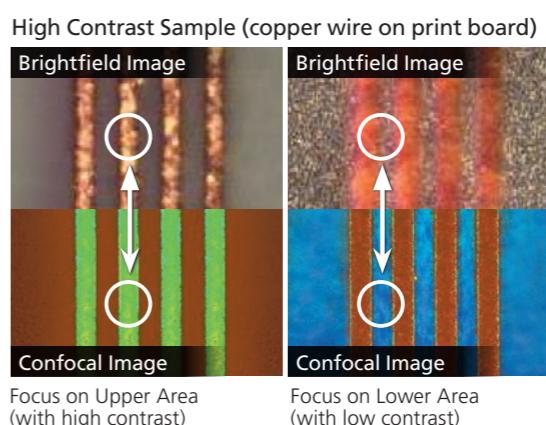


3D Image: simultaneous detection of the highest point of all wires

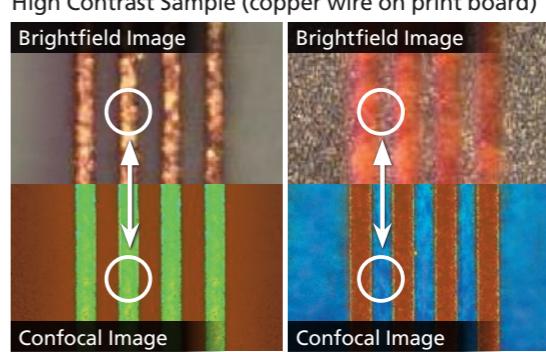
3D Image: display of wire height profile

Precise PCB Pattern

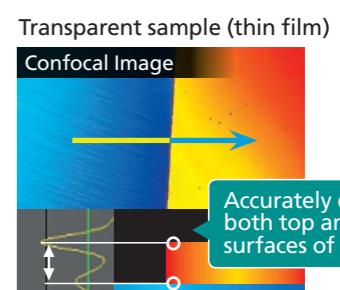
Accurate measurement of high contrast samples tends to be difficult with brightfield illumination because their edges appear unclear. Confocal optics enables a clear display, and facilitates accurate detection of sample edges.



Focus on Upper Area (with high contrast)



Focus on Lower Area (with low contrast)



Accurately detect both top and bottom surfaces of thin film

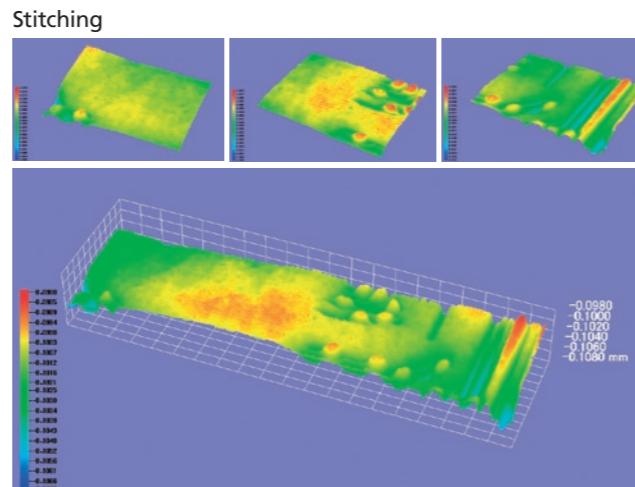
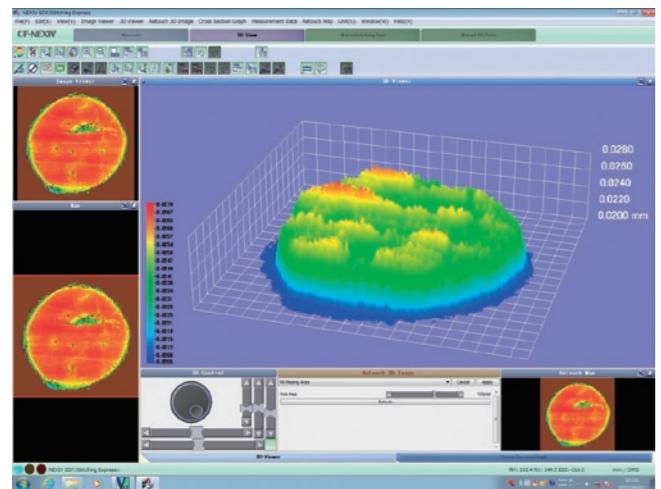


Capable of measuring thickness of thin film

Optional Software

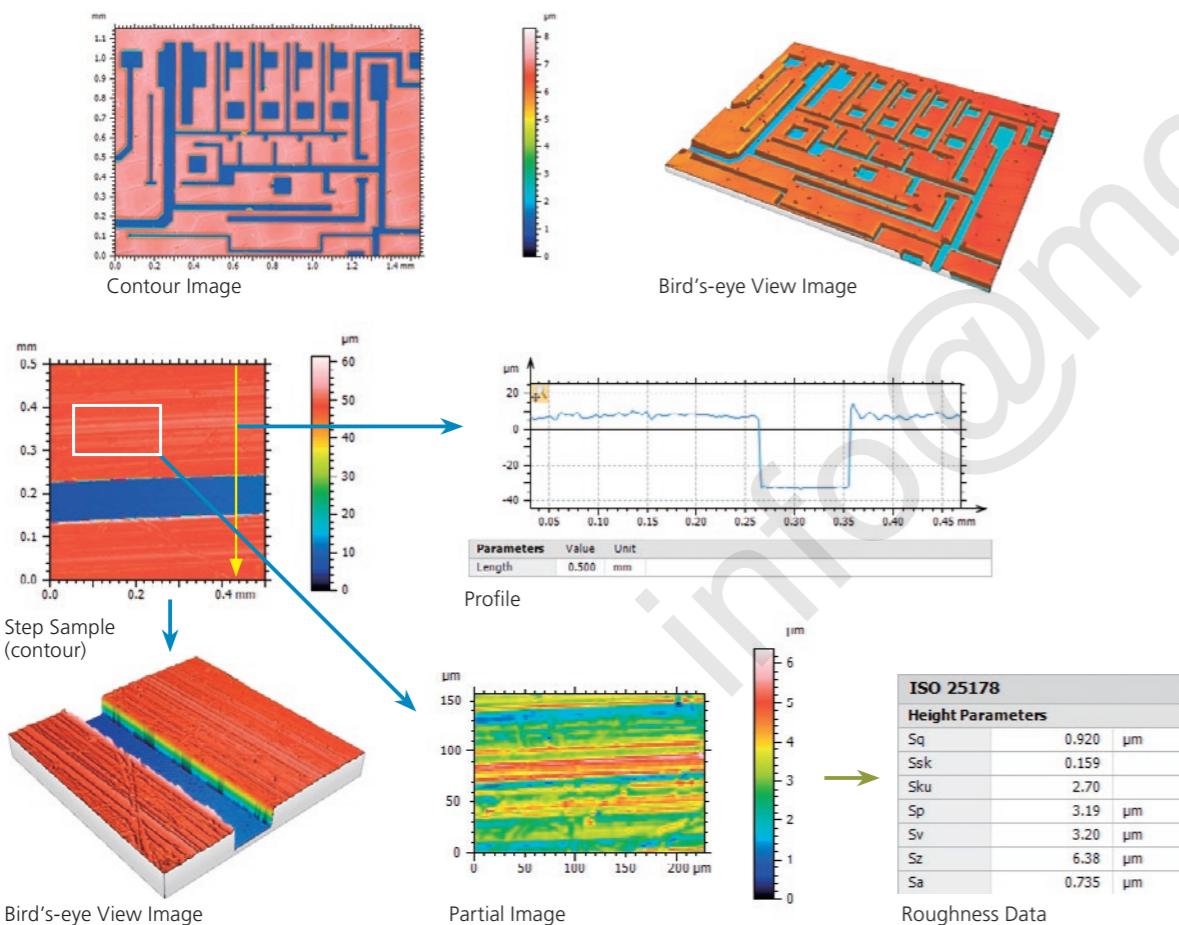
Image Archiving and Processing Software - EDF/Stitching Express

The EDF/Stitching Express software creates an image archiving library for confocal and brightfield images, and provides post-image processing functionalities, such as EDF and large-area image stitching.



3D Surface Metrology Analysis Software - MountainsMap X

The MountainsMap X is a powerful software for surface metrology analysis. It provides the rich functionality of 3D visualization, cross-sectional view, 2D and 3D roughness, and other parameters based on the latest ISO standards.

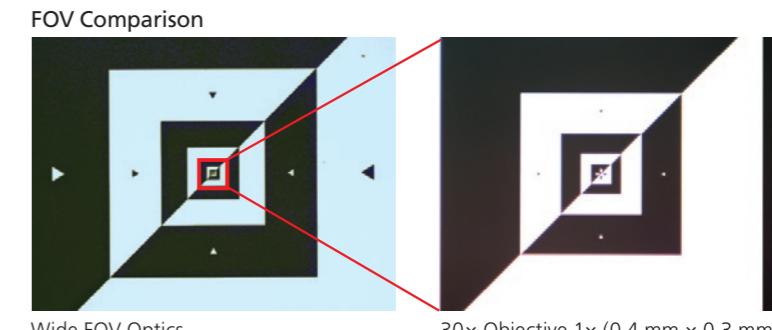
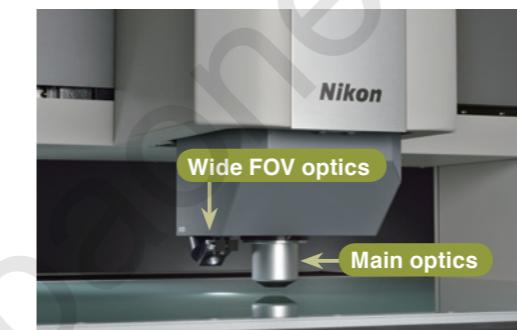
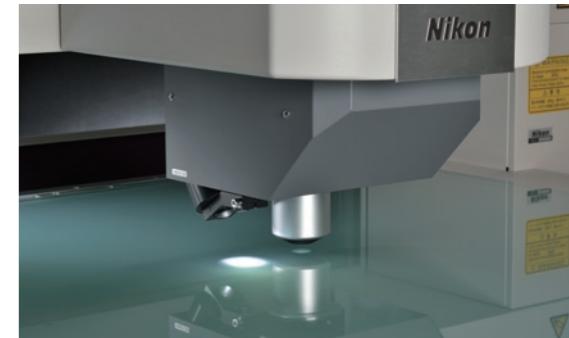


Optional Hardware

Wide FOV Optics (for high-magnification optical heads)

Wide field of view optics aids in the selection of the area to be measured and the creation of programs with high-magnification optical heads.

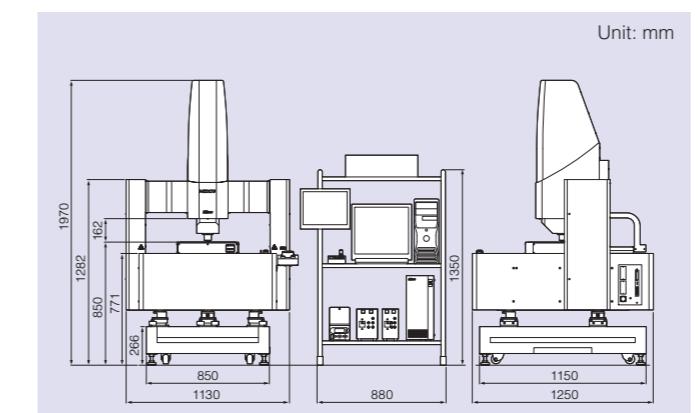
Compatible optical head	15x, 30x
Field of view	4.8 mm x 3.6 mm
Working distance	40.6 mm
Main optical head offset	64 mm
Illumination	Episcopic illumination only
Wide FOV optics effective ranges (mm)	VMZ-K3040: 236(X) x 400(Y) VMZ-K6555: 586(X) x 550(Y)



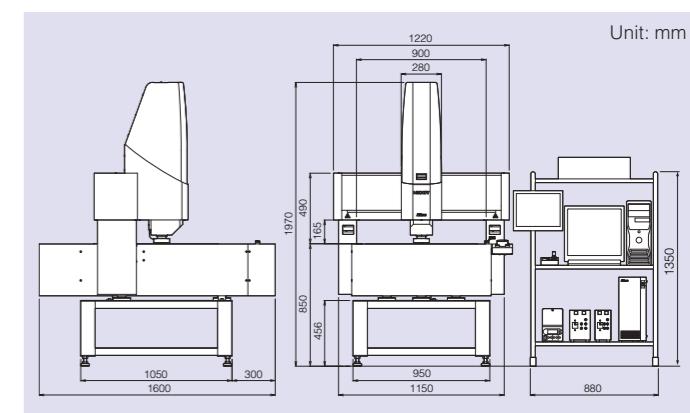
30x Objective 1x (0.4 mm x 0.3 mm)

Dimensional Diagram

VMZ-K 3040



VMZ-K 6555



Specifications

Model	VMZ-K3040 Type-S			VMZ-K3040 Type-H			VMZ-K6555 Type-S			VMZ-K6555 Type-H								
	Standard head			High-magnification head			Standard head			High-magnification head								
Objectives																		
Magnification	1.5x	3x	7.5x	15x	30x		1.5x	3x	7.5x	15x	30x							
Working distance (*with ring illumination)	24 mm*	24 mm	5 mm	20 mm	5 mm	24 mm*	24 mm	5 mm	20 mm	5 mm								
Confocal Optics (Area height measurement)																		
Maximum scan height	1 mm																	
Field of view	8x6 mm	4x3 mm	1.6x1.2 mm	0.8x0.6 mm	0.4x0.3 mm	8x6 mm	4x3 mm	1.6x1.2 mm	0.8x0.6 mm	0.4x0.3 mm								
Height measurement repeatability (2σ)	0.6 μm	0.35 μm	0.25 μm	0.25 μm	0.2 μm	0.6 μm	0.35 μm	0.25 μm	0.25 μm	0.2 μm								
Height resolution	0.01 μm																	
Field of view	8x6 to 0.53x0.4 mm	4x3 to 0.27x0.2 mm	1.6x1.2 to 0.11x0.08 mm	1.26x0.95 to 0.1x0.074 mm	0.63x0.47 to 0.05x0.04 mm	8x6 to 0.53x0.4 mm	4x3 to 0.27x0.2 mm	1.6x1.2 to 0.11x0.08 mm	1.26x0.95 to 0.1x0.074 mm	0.63x0.47 to 0.05x0.04 mm								
Illumination	Diascopic, coaxial episcopic and ring			Diascopic and coaxial episcopic			Diascopic, coaxial episcopic and ring			Diascopic and coaxial episcopic								
Light source	White LED																	
Autofocus	Vision AF, Laser AF																	
Main Body																		
XYZ strokes	300 mm × 400 mm × 150 mm					650 mm × 550 mm × 150 mm												
Accuracy guaranteed loading capacity	20kg					30kg												
Maximum permissible error (L: Length in mm)	EUX, MPE: 1.5 + 4L/1000 μm EUXY, MPE: 2.5 + 4L/1000 μm EUZ, MPE: 1 + L/1000 μm					EUX, MPE: 1.5 + 2.5L/1000 μm EUXY, MPE: 2.5 + 2.5L/1000 μm EUZ, MPE: 1 + L/1000 μm												
Power source	AC 100 – 240 V ± 10% 50/60 Hz																	
Power consumption	10A – 5A																	
Operating conditions	Temperature: 20°C ± 0.5 K, Humidity: 70 % or less																	
Acquired standard	CE marking (low voltage/EMC/laser)																	
Dimensions and weight																		
Main body and table	1130 × 1250 × 1970 mm / approx. 800 kg					1220 × 1600 × 1970 mm approx. 800 kg												
Controller	190 × 450 × 440 mm / 20 kg																	
Installation area (WxD)	2500 × 1600 mm					2500 × 1900 mm												

*Please contact Nikon for permissible floor vibration specifications.

Specifications and equipment are subject to change without any notice or obligation on the part of the manufacturer. July 2021 ©2011-2021 NIKON CORPORATION

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